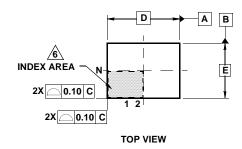
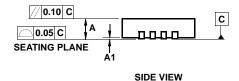
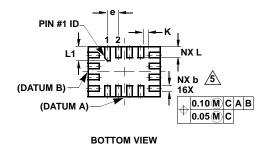
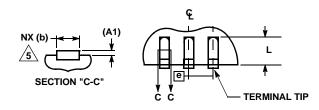
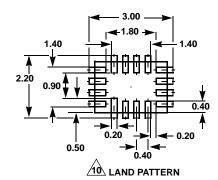
## Ultra Thin Quad Flat No-Lead Plastic Package (UTQFN)











L16.2.6x1.8A

16 LEAD ULTRA THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE

	MILLIMETERS			
SYMBOL	MIN	NOMINAL	MAX	NOTES
Α	0.45	0.50	0.55	-
A1	-	-	0.05	-
A3	0.127 REF			-
b	0.15	0.20	0.25	5
D	2.55	2.60	2.65	-
E	1.75	1.80	1.85	-
е	0.40 BSC			-
K	0.15	-	-	-
L	0.35	0.40	0.45	-
L1	0.45	0.50	0.55	-
N	16			2
Nd	4			3
Ne	4			3
θ	0	-	12	4

Rev. 6 1/14

## NOTES:

- 1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
- 2. N is the number of terminals.
- 3. Nd and Ne refer to the number of terminals on D and E side, respectively.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.25mm from the terminal tip.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Maximum package warpage is 0.05mm.
- 8. Maximum allowable burrs is 0.076mm in all directions.
- 9. JEDEC Reference MO-255.
- For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.